



# SHRI VISHWAKARMA SKILL UNIVERSITY



**Mapped with India  
Semiconductor Mission**

**First Skill University of India,  
setup by Govt. of Haryana**

## PG Diploma in Semiconductor Device Packaging

### PGDSDP



**Department:**

**Skill Department of Industry 4.0**

**Eligibility:**

- ▶ B.E /B.Tech. in Electronics/Electronics & Communication / Electrical/ Electrical and Electronics/Instrumentation/ Biomedical /Computer Science/Information Technology/ or M.Sc. in Electronics/Physics (with relevant specialization) with Minimum 50% aggregate
- ▶ Final year students of B.E./B.Tech. programs in the above-mentioned streams, are also eligible to apply.
- ▶ Basic knowledge of semiconductor devices and circuits preferred

**NCrF LEVEL:** 6.5

**Fees:** 30000/- per Semester

**SEATS:** 20

**Duration:** 1 Year

### About the Program

With India's semiconductor packaging ecosystem rapidly growing under the India Semiconductor Mission (ISM), there is an urgent demand for industry-ready professionals, especially in Assembly, Testing, Marking, and Packaging (ATMP) roles.

### Key Features

**Strategic Location:** Proximity to industrial hubs in Palwal, Bhiwadi, Manesar, Gurugram, and Noida.

**OJT-Focused Curriculum:** The 40 to 50% of the program is conducted on-site in industry.

**Industry-Vetted Capstone Projects:** Co-supervised by senior packaging engineers.

**Guest Sessions:** Lectures and technical talks by industry experts.

**ADMISSIONS OPEN 2025-26**

**For Admission Related Queries :**

**Vill. Dudhola, Distt. Palwal, Haryana-121102**

**Mr. Sansh Bir Dagar : 9813891890 / 9306095464 | Website : www.svsu.ac.in**

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## **PG Diploma in Semiconductor Device Packaging (PGDSDP)**

### **Eligibility Criteria:**

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- Basic knowledge of semiconductor devices and circuits preferred

**NCrF Level:** 6.5

**Seat:** 20

**Fees:** 30000/- Per semester

**Duration:** 1 Year

**Mode:** Full-Time + On-Job Training (OJT)

### **About the Program:**

With India's semiconductor packaging ecosystem rapidly growing under the India Semiconductor Mission (ISM), there is an urgent demand for industry-ready professionals, especially in Assembly, Testing, Marking, and Packaging (ATMP) roles.

### **Objective and Features of Program**

SVSU's applied skill-based education model ensures graduates are job-ready from Day 1, combining classroom theory with On Job Training in core Industry.

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